 Inputs Are TTL-Voltage Compatible Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption 	CD54ACT109 F PACKAGE CD74ACT109 E OR M PACKAGE (TOP VIEW)
 Balanced Propagation Delays 	
 ±24-mA Output Drive Current Fanout to 15 F Devices 	1J [2 15] 2CLR 1K [3 14] 2J
 SCR-Latchup-Resistant CMOS Process and Circuit Design 	1CLK 4 13 2K 1PRE 5 12 2CLK 1Q 6 11 2PRE
 Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015 	1Q [7 10] 2Q GND [8 9] 2Q
description/ordering information	

description/ordering information

The 'ACT109 devices contain two independent J- \overline{K} positive-edge-triggered flip-flops. A low level at the preset (PRE) or clear (\overline{CLR}) inputs sets or resets the outputs, regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the J and \overline{K} inputs meeting the setup-time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the J and \overline{K} inputs can be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by grounding \overline{K} and tying J high. They also can perform as D-type flip-flops if J and \overline{K} are tied together.

ORDERING INFORMATION

T _A	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – E Tube CD74ACT	CD74ACT109E	CD74ACT109E		
–55°C to 125°C	SOIC – M	Tube	CD74ACT109M	ACT109M	
-55 C 10 125 C	301C – M	Tape and reel	CD74ACT109M96	ACTIOSIM	
	CDIP – F	Tube	CD54ACT109F3A	CD54ACT109F3A	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	(each flip-flop)										
		OUT	PUTS								
PRE	CLR	CLK	J	ĸ	Q	Q					
L	Н	Х	Х	Х	Н	L					
н	L	Х	Х	Х	L	н					
L	L	Х	Х	Х	н†	H‡					
н	Н	\uparrow	L	L	L	Н					
н	Н	\uparrow	н	L	Тор	ggle					
н	Н	\uparrow	L	н	Q0	Q 0					
н	Н	\uparrow	Н	н	н	L					
н	Н	L	Х	Х	Q0	Q 0					

[‡] Unpredictable and unstable condition if both PRE and CLR go high simultaneously after both being low at the same time



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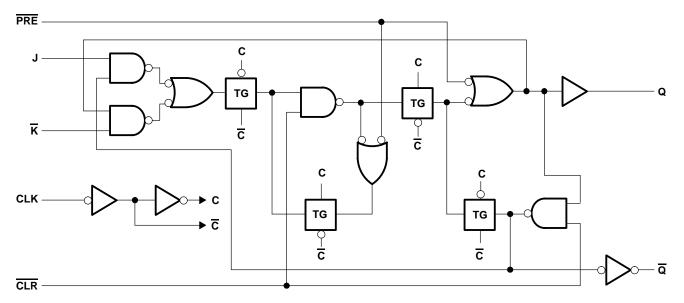
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logic diagram, each flip-flop (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 6 V
Input clamp current, I_{IK} ($V_I < 0$ V or $V_I > V_{CC}$) (see Note 1)	
Output clamp current, I_{OK} (V _O < 0 V or V _O > V _{CC}) (see Note 1)	±50 mA
Continuous output current, $I_O (V_O > 0 V \text{ or } V_O < V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 2): E package	67°C/W
M package	73°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		T _A = 25°C		–55° 125		–40° 85°		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
VIL	Low-level input voltage		0.8		0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	0	VCC	V
Vo	Output voltage	0	VCC	0	VCC	0	VCC	V
ЮН	High-level output current		-24		-24		-24	mA
IOL	Low-level output current		24		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10		10	ns/V

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	IDITIONS	Vcc	T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX		
		I _{OH} = -50 μA	4.5 V	4.4		4.4		4.4			
VOH		I _{OH} = -24 mA	4.5 V	3.94		3.7		3.8		V	
	$V_{I} = V_{IH} \text{ or } V_{IL}$	I _{OH} = -50 mA [†]	5.5 V			3.85				v	
		I _{OH} = -75 mA†	5.5 V					3.85			
	VI = VIH or VIL	I _{OL} = 50 μA	4.5 V		0.1		0.1		0.1		
Max		I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44		
VOL		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65				
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V						1.65		
l	$V_I = V_{CC}$ or GND		5.5 V		±0.1		±1		±1	μA	
ICC	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		4		80		40	μA	
∆I _{CC} ‡	V _I = V _{CC} -2.1 V		4.5 V to 5.5 V		2.4		3		2.8	mA	
Ci					10		10		10	pF	

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

‡ Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

ACT INPUT LOAD TABLE

INPUT	UNIT LOAD
J or CLK	1
ĸ	0.53
CLR or PRE	0.58

Unit Load is ΔI_{CC} limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).

timing requirements over recommended operating conditions (unless otherwise noted)

							UNIT
			MIN	MAX	MIN	MAX	
fclock	Clock frequency			100		114	MHz
	Dulas duration	CLK high or low	5		4.4		
tw	Pulse duration	CLR or PRE low	5.5		4.8		ns
t _{su}	Setup time, before CLK↑	J or K	5.5		4.8		ns
^t h	Hold time, after CLK↑	J or K	0		0		ns
t _{rec}	Recovery time, before CLK↑	CLR↑ or PRE↑	2.5		2.2		ns



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switching characteristics over recommended operating free-air temperature range, V_{CC} = $\,$ 5 V \pm 0.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

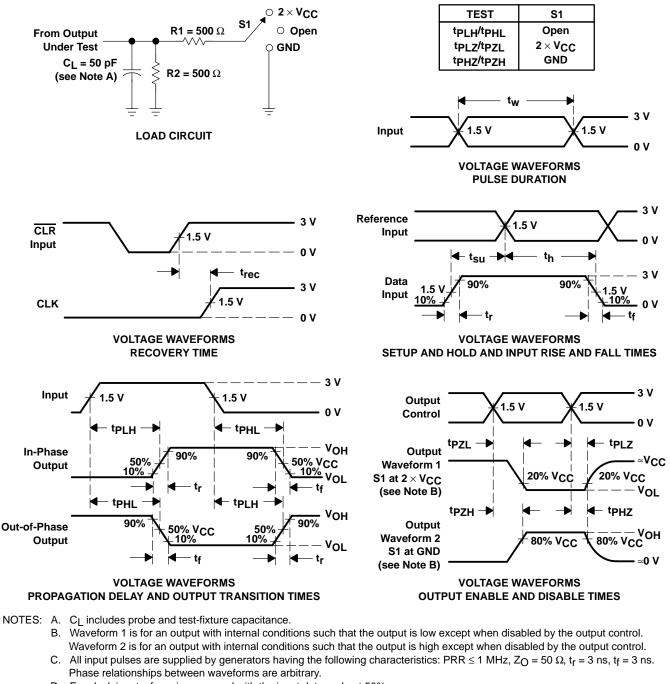
PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55° 125		–40°(85°	UNIT	
		(6611 61)	MIN	MAX	MIN	MAX	
fmax			100		114		MHz
t =	CLK		2.6	10.3	2.7	9.4	
^t PLH	CLR or PRE	Q or Q	3.1	12.2	3.2	11.1	ns
to	CLK	Q or \overline{Q}	2.6	10.3	2.7	9.4	00
^t PHL	CLR or PRE		3.1	12.2	3.2	11.1	ns

operating characteristics, V_{CC} = 5 V, T_A = 25° C

	PARAMETER	TYP	UNIT
Cpd	Power dissipation capacitance	56	pF



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PARAMETER MEASUREMENT INFORMATION

- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. tp71 and tp7H are the same as ten.
- H. tpLz and tpHz are the same as tdis.
- I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
	(.)					(=)	(6)	(0)		(,	
CD54ACT109F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54ACT109F3A	Samples
CD74ACT109E	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74ACT109E	Samples
CD74ACT109EE4	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74ACT109E	Samples
CD74ACT109M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT109M	Samples
CD74ACT109M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT109M	Samples
CD74ACT109M96E4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT109M	Samples
CD74ACT109ME4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT109M	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



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PACKAGE OPTION ADDENDUM

14-Aug-2021

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD54ACT109, CD74ACT109 :

• Catalog : CD74ACT109

• Military : CD54ACT109

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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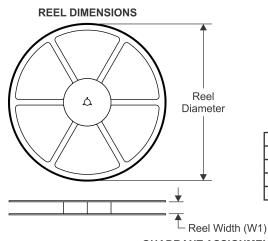
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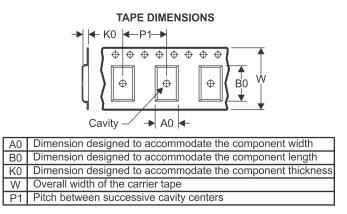
Pin1

Quadrant

Q1

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal											
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)
CD74ACT109M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0



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PACKAGE MATERIALS INFORMATION

27-Jul-2021



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74ACT109M96	SOIC	D	16	2500	340.5	336.1	32.0

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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